TEC0330 TRM

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Overview

The Trenz Electronic TEC0330 FPGA board is a PCI Express form factor card (PCIe 2.0 or higher) integrating the Xilinx Virtex-7 XC7VX330T FPGA chip. This high-end FPGA card is designed for maximum system performance and intended for use in applications with high demands on system throughput. There is a SO-DIMM socket on the board for standard DDR3 SDRAM extension memory module.

The TEC0330 features HPC (High Pin Count) ANSI/VITA 57.1 compatible FMC interface connector for standard I/O Mezzanine modules. Other interface connectors found on-board include JTAG for accessing FPGA and on-board System Controller CPLD, and also connector with 5 high-speed I/O differential signaling pairs.

The TEC0330 FPGA board is intended to be used as add-on card in a PCIe 2.0 or higher capable host systems, it can not be used as a stand-alone device.

Key Features

- Xilinx Virtex-7 FPGA module XC7VX330T-2FFG1157C (commercial temperature range)
- PCI Express 2.0 x8 card with maximum throughput of 4 GB/s
- FMC High Pin Count (HPC) connector
- 8 FPGA MGT lanes available on PCIe interface
- DDR3 SO-DIMM SDRAM socket
- 256-Mbit (32-MByte) Quad SPI Flash memory (for configuration and operation) accessible through: ° FPGA
 - JTAG port (SPI indirect, bus width x4)
- · External clock input via SMA coaxial connector
- 28 GTH transceivers, each with up to 13.1 Gbit/s data transmission rate
- FPGA configuration through:

 - JTAG connector
 Quad SPI Flash memory
- Programmable quad clock generator
- TI LMK04828B ultra low-noise JESD204B compliant clock jitter cleaner
- On-board high-efficiency DC-DC converters
 Up to 202 FPGA I/O pins available on FMC connector (up to 101 LVDS pairs possible)
- System management and power sequencing
- AES bit-stream encryption
- eFUSE bit-stream encryption

Additional assembly options are available for cost or performance optimization upon request.

Block Diagram

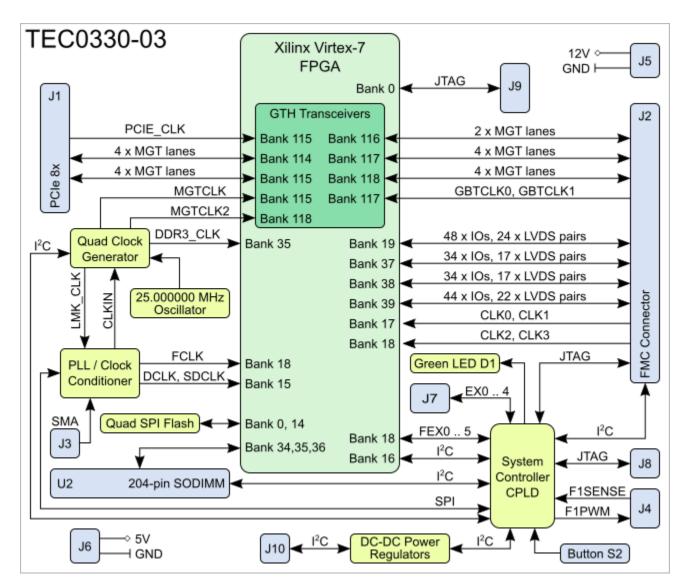


Figure 1: TEC0330-03 block diagram.

Main Components

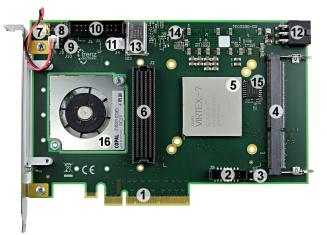




Figure 2: FPGA board TEC0330-03.

- 1. PCI Express 2.0 x8 connector, J1
- 2. FPGA JTAG connector, J9
- 3. User button, S2
- 4. SO-DIMM socket, U2
- 5. Xilinx Virtex-7 XC7VX330T-2FFG1157C FPGA, U1
- 6. ANSI/VITA 57.1 compliant FMC HPC connector, J2
- 7. SMA coaxial connector for external clock input, J3
- 8. System Controller CPLD JTAG connector, J8
- **9.** I²C connector for LT LTM4676 step-down DC-DC regulator, J10
- 10. IDC header for access to 5 x high-speed data lanes (LVDS pairs), J7
- **11.** 4-wire PWM fan connector, J4
- 12. 6-pin 12V power connector, J5
- 13. Reference clock generator @10.0 MHz (P5146) , U11
- 14. LDO DC-DC regulator @3.3V (LMK_3V3) (TI TPS74901RGWR), U21
- 15. 256 Mbit Quad SPI Flash Memory (Micron N25Q256A), U12
- 16. Cooling fan 5VDC M1 (45X5MM, 0.7W, 1.06CFM)
- 17. System Controller CPLD (Lattice Semiconductor LCMXO2-1200HC), U5
- **18.** Ultra low jitter clock synthesizer (TI LMK04828B), U9
- 19. Step-down DC-DC regulator @1.0V (LT LTM4676), U4
- 20. Step-down DC-DC regulator @1.5V (VCC1V5) (LT LTM4676, U3
- 21. I²C Programmable quad clock generator (Silicon Labs Si5338A), U13
- 22. 4A PowerSoC DC-DC converter @1.8V (Altera EN6347QI, U20
- 23. LDO DC-DC regulator @1.0V (MGTAVCC_FPGA) (TI TPS74401RGW), U18
- 24. LDO DC-DC regulator @1.2V (MGTAVTT_FPGA) (TI TPS74401RGW), U17
- 25. 4A PowerSoC DC-DC converter @3.3V (3V3FMC) (Altera EN6347QI), U15
- 26. 4A PowerSoC DC-DC converter @1.8V (FMC_VADJ) (Altera EN6347QI), U7

Initial Delivery State

| Storage device name | Content | Notes |
|---------------------------|-----------------------|--|
| SPI Flash OTP Area | Empty, not programmed | Except serial number programmed by flash vendor. |
| SPI Flash Quad Enable bit | Programmed | - |
| SPI Flash main array | Demo design | - |
| eFUSE USER | Not programmed | - |
| eFUSE Security | Not programmed | - |

Table 1: Initial delivery state.

Signals, Interfaces and Pins

FMC Connector

The high-pin count (HPC) FMC (FPGA Mezzanine Card) connector (J2) is a standard ANSI/VITA 57.1 modular interface to the FPGA and provides access to numerous FPGA I/O pins for use by other mezzanine modules and expansion cards. The FMC connector supports single ended I/O (with several VCCIO voltages available) and LVDS I/O signaling.

The I/O signals are routed from the FPGA I/O banks to the FMC connector as LVDS pairs:

| FPGA Bank | I/O Signals | LVDS pairs | Bank Voltage (VCCO) | Notes |
|--------------|----------------|---------------|------------------------|--|
| Bank 19 | 92 | 46 | 1.8V | - |
| Bank 39 | 42 | 21 | VIO_B_FMC | Bank voltage VIO_B_FMC must be supplied by FMC connector pins J2-J39, J2-K40. Bank's VREF_B_M2C signal is routed to the FMC connector pin J2-K1 (external reference voltage). |
| Bank 37 | 34 | 17 | 1.8V | Bank's VREF_A_M2C signal is routed to the FMC connector pin J2-H1 (external reference voltage). |
| Bank 38 | 34 | 17 | 1.8V | Bank's VREF_A_M2C signal is routed to the FMC connector pin J2-H1 (external reference voltage). |

Table 2: Overview of the FPGA I/O bank signals routed to the FMC.

There are also 10 high-speed MGT lanes (Xilinx GTH transceivers) from different FPGA MGT banks routed to the FMC connector. Following MGT lanes are available on the FMC connector:

| FPGA Bank | I/O Signals | LVDS Pairs | MGT Lanes | MGT Bank's Reference Clock |
|--------------|----------------|---------------|--------------|--|
| 116 | 8 | 4 | 2 | 1 clock-signal from clock synthesizer U9 to bank's pins T6/T5. |
| 117 | 16 | 8 | 4 | 2 clock-signals from clock FMC connector GBTCLK0_M2C and GBTCLK1_M2C (pins J2-D4/J2-D5 and J2-B20/J2-B21) to bank's pins M6/M5 and P6/P5. |
| 118 | 16 | 8 | 4 | reference clock from clock synthesizer U9 to bank's pins F6/F5 reference clock from programmable quad clock generator U13 to bank's pins H6/H5. |

Table 3: Overview of MGT banks lanes routed to the FMC connector.

The FMC connector has also two reference clock input pairs (LVDS) routed to the FPGA MGT bank 117, see also section MGT lanes.

There are also JTAG, I²C interface and power good control signals routed between FMC connector and System Controller CPLD:

| Interface | I/O Signals | Schematic Name / FMC Pin | Connected to | Notes |
|-----------|-------------|--------------------------|--------------|-------|
|-----------|-------------|--------------------------|--------------|-------|

| JTAG | 5 | FMC_TRST, pin D34 | SC CPLD, bank 2 | VCCIO: 3V3PCI. |
|------------------|---|-------------------------------------|-----------------|--|
| | | FMC_TCK, pin D29 | | |
| | | FMC_TMS, pin D33 | | |
| | | FMC_TDI, pin D30 | | |
| | | FMC_TDO, pin D31 | | |
| l ² C | 2 | FMC_SCL, pin C30 | SC CPLD, bank 2 | VCCIO: 3V3PCI. |
| | | FMC_SDA, pin C31 | | I ² C-lines 3V3PCI pulled-up. |
| Control lines | 3 | FMC_PRSNT_M2C_L, pin H2 | SC CPLD, bank 1 | PG - Power Good signal. |
| | | FMC_PG_C2M, pin D1 (3V3FMC pull-up) | | C2M - carrier to mezzanine module. |
| | | FMC_PG_M2C, pin F1 (3V3FMC pull-up) | | M2C - mezzanine module to carrier. |
| | | | | Internal System Controller CPLD signal assignment: |
| | | | | FEX_0_N <= FMC_PG_M2C |
| | | | | FMC_PG_C2M <= FMC_PRSNT_M2C_L |

Table 4: FMC connector pin-outs of available interfaces to the System Controller CPLD.

FPGA bank 17 and 18 clock inputs from FMC connector:

| Schematic Name | FMC Connector Pins | FPGA Bank | FPGA Pins |
|----------------|--------------------|-----------|-----------|
| CLK0_P, CLK0_N | H4, H5 | 17 | R28, R29 |
| CLK1_P, CLK1_N | G2, G3 | 17 | P29, P30 |
| CLK2_P, CLK2_N | K4, K5 | 18 | G31, G31 |
| CLK3_P, CLK3_N | J2, J3 | 18 | H29, H30 |

 Table 5:
 FMC connector pin-outs for reference clock input.

Several VCCIO voltages are available on the FMC connector for FPGA I/O banks:

| Schematic Name | Max Current | FMC Connector Pins | Notes |
|----------------|-----------------|--------------------|---|
| 12V | 1A | C35, C37 | Externally supplied 12V |
| 3V3PCI | 20mA | D32 | Supplied by the PCIe interface |
| 3V3FMC | 3A | D36, D38, D40, C39 | Supplied by DC-DC converter U15 |
| VIO_B_FMC | External supply | J39, K40 | Externally supplied VCCO to HB FPGA bank 39 |
| FMC_VADJ | 4A | H40, G39, F40, E39 | Fixed to 1.8V, supplied by DC-DC converter U7 |

Table 6: Available VCCIO voltages on FMC connector.

PCI Express Interface

The TEC0330 FPGA board is a PCI Express card designed to fit into systems with PCI Express x8 slots (PCIe 2.0 or higher) and is PCIe Gen. 2 capable. See next section for the overview of FPGA MGT lanes routed to the PCIe interface.

MGT Lanes

MGT (Multi Gigabit Transceiver) lane consists of one receive and one transmit (RX/TX) differential pairs, four signals total per one MGT lane. Following table lists lane number, MGT bank number, transceiver type, signal schematic name, FMC connector pin connection and FPGA pin connection information.

FPGA to FMC Connector MGT lanes

| Lane | FPGA Bank | Туре | Signal Name | FPGA Pin | FMC Pin |
|------|-----------|------|--|--|--|
| 0 | 117 | GTH | DP0_M2C_P DP0_M2C_N DP0_C2M_P DP0_C2M_N | MGTHRXP0_117, N4 MGTHRXN0_117, N3 MGTHTXP0_117, M2 MGTHTXN0_117, M1 | J2A-C6 J2A-C7 J2A-C2 J2A-C3 |
| 1 | 117 | GTH | DP1_M2C_P DP1_M2C_N DP1_C2M_P DP1_C2M_N | MGTHRXP1_117, L4 MGTHRXN1_117, L3 MGTHTXP1_117, K2 MGTHTXN1_117, K1 | J2A-A2 J2A-A3 J2A-A22 J2A-A23 |
| 2 | 117 | GTH | DP2_M2C_P DP2_M2C_N DP2_C2M_P DP2_C2M_N | MGTHRXP2_117, K6 MGTHRXN2_117, K5 MGTHTXP2_117, H2 MGTHTXN2_117, H1 | J2A-A6 J2A-A7 J2A-A26 J2A-A27 |
| 3 | 117 | GTH | DP3_M2C_P DP3_M2C_N DP3_C2M_P DP3_C2M_N | MGTHRXP3_117, J4 MGTHRXN3_117, J3 MGTHTXP3_117, F2 MGTHTXN3_117, F1 | J2A-A10 J2A-A11 J2A-A30 J2A-A31 |
| 4 | 118 | GTH | DP4_M2C_P DP4_M2C_N DP4_C2M_P DP4_C2M_N | MGTHRXP0_118, G4 MGTHRXN0_118, G3 MGTHTXP0_118, D2 MGTHTXN0_118, D1 | J2A-A14 J2A-A15 J2A-A34 J2A-A35 |

Table 8: FPGA to FMC connector MGT lanes overview (continue on next page).

FPGA to FMC Connector MGT lanes (continued)

| Lane | FPGA Bank | Туре | Signal Name | FPGA Pin | FMC Pin |
|------|-----------|------|--|--|--|
| 5 | 118 | GTH | DP5_M2C_P DP5_M2C_N DP5_C2M_P DP5_C2M_N | MGTHRXP1_118, E4 MGTHRXN1_118, E3 MGTHTXP1_118, C4 MGTHTXN1_118, C3 | J2A-A18 J2A-A19 J2A-A38 J2A-A39 |
| 6 | 118 | GTH | DP6_M2C_P DP6_M2C_N DP6_C2M_P DP6_C2M_N | MGTHRXP2_118, D6 MGTHRXN2_118, D5 MGTHTXP2_118, B2 MGTHTXN2_118, B1 | J2A-B16 J2A-B17 J2A-B36 J2A-B37 |
| 7 | 118 | GTH | DP7_M2C_P DP7_M2C_N DP7_C2M_P DP7_C2M_N | MGTHRXP3_118, B6 MGTHRXN3_118, B5 MGTHTXP3_118, A4 MGTHTXN3_118, A3 | J2A-B12 J2A-B13 J2A-B32 J2A-B33 |

| 8 | 116 | GTH | DP8_M2C_P DP8_M2C_N DP8_C2M_P DP8_C2M_N | MGTHRXP2_116, U4 MGTHRXN2_116, U3 MGTHTXP2_116, T2 MGTHTXN2_116, T1 | J2A-B8 J2A-B9 J2A-B28 J2A-B29 |
|---|-----|-----|--|--|--|
| 9 | 116 | GTH | DP9_M2C_P DP9_M2C_N DP9_C2M_P DP9_C2M_N | MGTHRXP3_116, R4 MGTHRXN3_116, R3 MGTHTXP3_116, P2 MGTHTXN3_116, P1 | J2A-B4 J2A-B5 J2A-B24 J2A-B25 |

 Table 8: FPGA to FMC connector MGT lanes overview.

FPGA to PCIe Connector MGT lanes

| Lane | FPGA Bank | Туре | Signal Name | FPGA Pin | PCle Pin |
|------|-----------|------|--|--|--|
| 0 | 115 | GTH | PER0_P PER0_N PET0_P PET0_N | MGTHRXP3_115, AB2 MGTHRXN3_115, AB1 MGTHTXP3_115, AC4 MGTHTXN3_115, AC3 | J1-A16 J1-A17 J1-B14 J1-B15 |
| 1 | 115 | GTH | PER1_P PER1_N PET1_P PET1_N | MGTHRXP2_115, AD2 MGTHRXN2_115, AD1 MGTHTXP2_115, AE4 MGTHTXN2_115, AE3 | J1-A21 J1-A22 J1-B19 J1-B20 |
| 2 | 115 | GTH | PER2_P PER2_N PET2_P PET2_N | MGTHRXP1_115, AF2 MGTHRXN1_115, AF1 MGTHTXP1_115, AF6 MGTHTXN1_115, AF5 | J1-A25 J1-A26 J1-B23 J1-B24 |
| 3 | 115 | GTH | PER3_P PER3_N PET3_P PET3_N | MGTHRXP0_115, AH2 MGTHRXN0_115, AH1 MGTHTXP0_115, AG4 MGTHTXN0_115, AG3 | J1-A29 J1-A30 J1-B27 J1-B28 |
| 4 | 114 | GTH | PER4_P PER4_N PET4_P PET4_N | MGTHRXP3_114, AK2 MGTHRXN3_114, AK1 MGTHTXP3_114, AJ4 MGTHTXN3_114, AJ3 | J1-A35 J1-A36 J1-B33 J1-B34 |
| 5 | 114 | GTH | PER5_P PER5_N PET5_P PET5_N | MGTHRXP2_114, AM2 MGTHRXN2_114, AM1 MGTHTXP2_114, AL4 MGTHTXN2_114, AL3 | J1-A39 J1-A40 J1-B37 J1-B38 |
| 6 | 114 | GTH | PER6_P PER6_N PET6_P PET6_N | MGTHRXP1_114, AN4 MGTHRXN1_114, AN3 MGTHTXP1_114, AM6 MGTHTXN1_114, AM5 | J1-A43 J1-A44 J1-B41 J1-B42 |

| | 7 | 114 | GTH | | | |
|-----------------------------|---|-----|-----|--|--|--|
| PET7_P MGTHTXP0_114, AP | | | | PER7_N PET7_P | MGTHRXP0_114, AP2 MGTHRXN0_114, AP1 MGTHTXP0_114, AP6 MGTHTXN0_114, AP5 | J1-A47 J1-A48 J1-B45 J1-B46 |

Table 9: FPGA to PCIe connector MGT lanes overview.

Following table lists reference clock sources of the MGT banks.

| Clock Signal | MGT Bank | Source | FPGA Pin | Notes |
|-----------------------|----------|-----------------|----------------------|------------------------------------|
| MGTCLK_5338_P | 115 | U13, CLK1A | MGTREFCLK0P_115, AB6 | On-board Si5338A. |
| MGTCLK_5338_N | 115 | U13, CLK1B | MGTREFCLK0N_115, AB5 | On-board Si5338A. |
| PCIE_CLK_P | 115 | J1-A13, REFCLK+ | MGTREFCLK1P_115, AD6 | External clock from PCIe slot. |
| PCIE_CLK_N | 115 | J1-A14, REFCLK- | MGTREFCLK1N_115, AD6 | External clock from PCIe slot. |
| CLK_SYNTH_DCLKOUT4_P | 116 | U9, DCLKout4 | MGTREFCLK0P_116, T6 | On-board LMK04828B. |
| CLK_SYNTH_DCLKOUT4_N | 116 | U9, DCLKout4* | MGTREFCLK0N_116, T6 | On-board LMK04828B. |
| GBTCLK0_M2C_P | 117 | J2-D4 | MGTREFCLK0P_117, M6 | External clock from FMC connector. |
| GBTCLK0_M2C_N | 117 | J2-D5 | MGTREFCLK0N_117, M5 | External clock from FMC connector. |
| GBTCLK1_M2C_P | 117 | J2-B20 | MGTREFCLK1P_117, P6 | External clock from FMC connector. |
| GBTCLK1_M2C_N | 117 | J2-B21 | MGTREFCLK1N_117, P5 | External clock from FMC connector. |
| CLK_SYNTH_SDCLKOUT7_P | 118 | U9, DCLKout7 | MGTREFCLK0P_118,F6 | On-board LMK04828B. |
| CLK_SYNTH_SDCLKOUT7_N | 118 | U9, DCLKout7* | MGTREFCLK0N_118,F5 | On-board LMK04828B. |
| MGTCLK2_5338_P | 118 | U13, CLK3A | MGTREFCLK1P_118, H6 | On-board Si5338A. |
| MGTCLK2_5338_N | 118 | U13, CLK3B | MGTREFCLK1N_118, H5 | On-board Si5338A. |

Table 10: MGT banks reference clock sources.

JTAG Interfaces

There are three JTAG interfaces available on the TEC0330 board:

| JTAG Interface | Signal Schematic Name | JTAG Connector Pin | Connected to |
|----------------|-----------------------|-----------------------|-------------------------|
| CPLD JTAG | CPLD_JTAG_TMS | J8-1 | SC CPLD, bank 0, pin 90 |
| VCCIO: 3V3PCI | CPLD_JTAG_TDI | J8-2 | SC CPLD, bank 0, pin 94 |
| Connector: J8 | CPLD_JTAG_TDO | J8-3 | SC CPLD, bank 0, pin 95 |
| | CPLD_JTAG_TCK | J8-4 | SC CPLD, bank 0, pin 91 |
| | | | |
| FPGA JTAG | FPGA_JTAG_TMS | J9-4 | FPGA, bank 0, pin N9 |
| VCCIO: 1V8 | FPGA_JTAG_TMS | J9-6 | FPGA, bank 0, pin M8 |
| Connector: J9 | FPGA_JTAG_TCK | J9-8 | FPGA, bank 0, pin N8 |
| | FPGA_JTAG_TDI | J9-10 | FPGA, bank 0, pin L8 |
| | | | |
| FMC JTAG | FMC_TRST | J2-D34 | SC CPLD, bank 2, pin 36 |

| VCCIO: 3.3VPCI | FMC_TRST | J2-D29 | SC CPLD, bank 2, pin 27 |
|----------------|----------|--------|-------------------------|
| Connector: J2 | FMC_TCK | J2-D33 | SC CPLD, bank 2, pin 28 |
| | FMC_TMS | J2-D30 | SC CPLD, bank 2, pin 31 |
| | FMC_TDO | J2-D31 | SC CPLD, bank 2, pin 32 |

Table 11: JTAG interfaces on TEC0330 board.

On-board Peripherals

System Controller CPLD

The System Controller CPLD is the central system management unit that provides numerous interfaces between the on-board peripherals and to the FPGA module. The signals routed to the CPLD will be linked by the logic implemented in the CPLD firmware, which generates output signals to control the system, the on-board peripherals and the interfaces. So some interfaces between the on-board peripherals and to the FPGA module are by-passed, forwarded and controlled by the System Controller CPLD.

Other tasks of the System Controller CPLD are the monitoring of the power-on sequence, the proper programing of the FPGA module and to display its programming state.

| SC CPLD Bank | CPLD Bank's VCCIO |
|--------------|-------------------|
| 0 | 3V3PCI |
| 1 | 3V3PCI |
| 2 | 3V3PCI |
| 3 | 1V8 |

Table 12: VCCIO voltages of CPLD banks.

Following table describes the interfaces and functionalities of the System Controller CPLD not described elsewhere in this TRM:

| CPLD Functionality | Interface | Designated CPLD Pins | Connected to | Notes |
|---|------------------------------|--|---|--|
| I ² C interface between on-board peripherals and FPGA | I ² C | FPGA_IIC_S DA, pin 24 FPGA_IIC_S CL, pin 25 FPGA_IIC_O E, pin 19 | FPGA bank 16, pin V29 FPGA bank 16, pin W29 FPGA bank 16, pin W26 | VCCIO: 1V8, all with pull-up to 1V8. Following devices and connectors are linked to the FPGA_IIC I ² C interface: • DC-DC converter U3 and U4 (LT LTM4676) • Programmable quad clock generator U13 • FMC connector J2 • PCIe connector J1 Note: FPGA_IIC_OE must kept high for I ² C operation. For I ² C slave device addresses refer to the component datasheets. |
| User I/Os External LVDS pairs | 10 I/Os 5 x LVDS pairs | EX0_P EX4_P EX0_N EX4_N | • IDC header J7 | Can also be used for single-ended signaling. |

| User I/Os | 13 I/Os | | | VCCIO: 1V8 |
|---|-----------------------------|---|--|---|
| Internal LVDS pairs | 6 x LVDS pairs | FEX0_P FEX5_P FEX0_N FEX5_N FEX_DIR (single-ended I/O) | • FPGA bank 18 | Can also be used for single-ended signaling. FPGA bank 18 has also reference clock input from FMC connector (CLK2, CLK3) and clock synthesizer U9 (FCLK). Internal signal assignment: FEX_DIR <= FMC_PRSNT_M2C_L |
| FPGA programming control and state | 2 I/Os | DONE, pin 7 PROGRAM_ B, pin 8 | FPGA bank 0, pin V8 FPGA bank 0, pin U8 | VCCIO: 1V8 |
| I ² C interface to programmable quad clock generator | l ² C | PLL_SCL, pin 14 PLL_SDA, pin 15 | U13, pin 12 U13, pin 19 | VCCIO: 1V8 Only PLL_SDA has 1V8 pull-up. |
| Fan PWM control J4 | 2 I/Os | F1SENSE, pin 99 F1PWM, pin 98 | J4-3 (active low) J4-4 | Internal signal assignment: • FEX_5_P <= F1SENSE • FEX_5_N => F1PWM |
| Button S2 | 1 I/O | BUTTON, pin 77 | Switch S2 | Functionality depends on CPLD firmware, activating pin PROGRAM_B (active low) and LED1 in standard configuration. |
| LED1 | 1 I/O | • LED1, pin 76 | LED D1 (green) | Fast blinking, when FPGA is not programmed. Internal signal assignment: • LED1 <= Button S2 or FEX0_P |
| PCIe control line RESET_B | 1 I/O | • PCIE_RSTB, pin 37 | • J1-A11 | Internal signal assignment: • FEX_4_N <= PCIE_RSTB |
| Control interface to clock synthesizer U9 (TI LMK04828B) | SPI (3 I /Os), 4 I/Os | CLK_SYNTH _SDIO, pin 75 CLK_SYNTH _SCK, pin 74 CLK_SYNTH _RESET, pin 54 CLK_SYNTH _CS, pin 53 CLK_SYNTH _SYNC, pin 52 LMK_STAT0, pin 62 LMK_STAT1, pin 63 | U9, pin 20 U9, pin 19 U9, pin 5 U9, pin 18 U9, pin 6 U9, pin 31 U9, pin 48 | Pull up to 3V3PCI. Internal signal assignment: LMK_SCK <= FEX_1_P LMK_SDIO <= FEX_1_N LMK_CS <= FEX_3_P LMK_SYNC <= EX_3_N LMK_RESET <= FEX_4_P FEX_2_P => LMK_SDIO (FEX_2_N must be 0) LMK_STAT0 and LMK_STAT1 signals are not used. |

| Control Interface to DC-DC converters U3 and U4 (both LTM4676) | I ² C (2 I/Os), 2 I/Os | LTM_SCL, pin 67 LTM_SDA, pin 66 LTM1_ALERT , pin 65 LTM2_ALERT , pin 64 | U4, pin E6 and U3, pin E6 U4, pin D6 and U3, pin D6 U4, pin E5 U3, pin E5 | 3V3 pull-ups. LTM I ² C interface is also accessible trough header J10. LTM1_ALERT and LTM2_ALERT signals are not used. |
|---|--------------------------------------|--|--|---|
| Power-on sequence and monitoring | 6 I/Os | EN_1V8, pin 58 PG_1V8, pin 59 EN_FMC_VA DJ, pin 60 PG_FMC_VA DJ, pin 61 EN_3V3, pin 51 PG_3V3, pin 57 | U20, pin 27 U20, pin 28 U7, pin 27 U7, pin 28 U15, pin 27 U15, pin 28 | Sequence of the supply voltages depend on the System Controller CPLD firmware. EN_1V8, EN_3V3 and EN_FMC_VADJ will be set simultaneously at start-up. PG signals will not be evaluated. |

Table 13: Overview of the System Controller CPLD functions.

SO-DIMM Socket for DDR3 SDRAM

The TEC0330 board supports additional DDR3 SO-DIMM via 204-pin socket U2. The DDR3 memory interface is routed to the FPGA banks 34, 35 and 36.

The reference clock signal for the DDR3 interface is generated by the quad programmable clock generator U13 and is applied to the FPGA bank 35.

There is also a I²C interface between the System Controller CPLD and the DDR3 SDRAM memory:

| Interface Signals Schematic Name | System Controller CPLD Pin | DDR3 Memory Interface Pin |
|----------------------------------|----------------------------|---------------------------|
| DDR3_SDA | Bank 2, pin 48 | Pin 200 (3V3PCI pull-up) |
| DDR3_SCL | Bank 2, pin 49 | Pin 202 (3V3PCI pull-up) |

Table 14: I²C-interface between SC CPLD and DDR3 SDRAM memory.

Quad SPI Flash Memory

An 256 Mbit (32 MByte) Quad SPI Flash Memory (Micron N25Q256A, U12) is provided for FPGA configuration file storage. After configuration process completes the remaining free memory can be used for application data storage. All four SPI data lines are connected to the FPGA allowing x1, x2 or x4 data bus widths to be used. The maximum data transfer rate depends on the bus width and clock frequency. The memory can be accessed indirectly by the FPGA JTAG port (J9) by implementing the functional logic for this purpose inside the FPGA.

Clock sources

The TEC0330 FPGA board has a sophisticated clock generation and conditioning system to meet the requirements of the Xilinx Virtex-7 GTH units with data transmission rates up to 13.1 Gb/s.

List of on-board and external reference clock signals of the TE0330 board:

| Clock Source | Schematic Name | Frequency | Clock Destination |
|---------------------------|--------------------------|-----------|----------------------------------|
| SMA coaxial connector, J3 | CLK_SYNTH_CLKIN0_P, | User | Clock synthesizer U9, pins 37/38 |
| | CLK_SYNTH_CLKIN0_N (GND) | | |

| RAKON P5146LF oscillator, U11 | - | 10.0 MHz | Clock synthesizer U9, pins 43/44 |
|---------------------------------|----------------|--------------|--|
| SiTime SiT8208 oscillator, U14 | CLK_25MHz | 25.0 MHz | Programmable quad clock generator U13, pin 3 |
| FMC connector J2, pins H4/H5 | CLK0_P, CLK0_N | User | FPGA bank 17, pins R28/R29 |
| FMC connector J2, pins G2/G3 | CLK1_P, CLK1_N | User | FPGA bank 17, pins P29/P30 |
| FMC connector J2, pins K4/K5 | CLK2_P, CLK2_N | User | FPGA bank 18, pins G30/G31 |
| FMC connector J2, pins J2/J3 | CLK3_P, CLK3_N | User | FPGA bank 18, pins H29/H30 |
| FMC connector J2, pins D4/D5 | GBTCLK0_M2C_P, | User | FPGA bank 117, pins M6/M5 |
| | GBTCLK0_M2C_N | | |
| FMC connector J2, pins B20/B21 | GBTCLK1_M2C_P, | User | FPGA bank 117, pins P6/P5 |
| | GBTCLK1_M2C_N | | |
| PCIe interface J1, pins A13/A14 | PCIE_CLK_P, | 100 MHz | FPGA bank 115, pins AD6/AD5 |
| | PCIE_CLK_N | (PCIe spec.) | |

Table 15: Clock generator sources overview.

Programmable Clock Generator

There is a Silicon Labs I²C programmable quad clock generator Si5338A (U13) on-board. It's output frequencies are programmable via FPGA I²C interface using slave device address 0x70 (corresponding I²C logic has to be implemented in FPGA design).

| Si5338A (U13) Input | Signal Schematic Name | Notes |
|-------------------------|--|---|
| IN1/IN2 | CLKIN_5338_C_P, CLKIN_5338_C_N | Reference clock signal from clock synthesizer U9 (100 nF decoupling capacitors and 100 termination resistor). |
| IN3 | Reference clock oscillator input, SiTime SiT8208AI (U14). | 25.0 MHz fixed frequency. |
| IN4/IN6 | Connected to the GND. | LSB (pin 'IN4') of the default I ² C-adress 0x70 is zero. |
| IN5 | Not connected | - |
| Si5338A (U13) Output | Signal Schematic Name | Notes |
| CLK0 A/B | DDR3_CLK_P, DDR3_CLK_N | DDR3-RAM reference clock signal to FPGA bank 35. |
| CLK1 A/B | MGTCLK_5338_C_P, MGTCLK_5338_C_N | Reference clock signal to FPGA bank 115 MGT (100 nF decoupling capacitors and 100 termination resistor). |
| CLK2 A/B | LMK_CLK_P, LMK_CLK_N | Input clock signal to clock synthesizer U9 (100 nF decoupling capacitors). |
| CLK3 A/B | MGTCLK2_5338_C_P, MGTCLK2_5338_C_N | Reference clock signal to FPGA bank 118 MGT (100 nF decoupling capacitors and 100 termination resistor). |

Table 16: I/O pin description of programmable clock generator Si5338A.

Ultra low-noise high-performance clock synthesizer

The TEC0330 board utilizes an ultra low jitter clock synthesizer TI LMK04828B (U9) for conditioning and generating clean clock signals which are necessary for the GTH units of the Xilinx Virtex-7 FPGA module.

The clock synthesizer can be controlled and programmed by its SPI interface (SPI slave) and other control lines, which are routed to the FPGA module (SPI master) and by-passed trough the System Controller CPLD. See section 'System Controller CPLD' for more detailed information.

Logic needs to be generated inside the FPGA module to utilize SPI bus correctly.

| LMK04828B (U9) input | signal schematic name | Note |
|---------------------------------|--|---|
| Status_LD1, Status_LD2 | LMK_STAT0, LMK_STAT1 | Connected to System Controller CPLD, not implemented in current CPLD firmware. |
| SPI interface and control lines | see section 'System controller CPLD' | The clock synthesizer IC is accessible to the FPGA via the SPI interface and control lines, which are routed through the System Controller CPLD. |
| CLKin0, CLKin0* | CLK_SYNTH_CLKIN0_P, CLK_SYNTH_CLKIN0_N | Input reference clock signal via SMA coaxial connector J3, connected to CLKin0* via serial decoupling capacitor 100nF. CLKin0 to connected to GND via serial decoupling capacitor 100nF. |
| CLKin1, CLKin1* | CLK_SYNTH_CLKIN1_P, CLK_SYNTH_CLKIN1_N | Input reference clock signal from programmable quad clock generator Si5338A (U13) via serial decoupling capacitor 100nF. |
| OSCin, OSCin* | - | Signal from reference clock oscillator RAKON P51446LF, fixed to 10.0 MHz. |
| LMK04828B (U9) output | signal schematic name | Note |
| DCLKout0, DCLKout0* | CLK_SYNTH_DCLKOUT 0_P, CLK_SYNTH_DCLKOUT | Reference clock signal to FPGA bank 15 pins AD29/AE29. |
| SDCLKout1, SDCLKout1* | 0_N CLK_SYNTH_SDCLKO UT1_P, CLK_SYNTH_SDCLKO UT1_N | Reference clock signal to FPGA bank 15 pins AE31/AF31. |
| DCLKout2, DCLKout2* | CLKIN_5338_P, CLKIN_5338_N | Reference clock signal to programmable quad clock generator Si5338A (U13) (100 nF decoupling capacitors and 100 termination resistor). |
| DCLKout4, DCLKout4* | CLK_SYNTH_DCLKOUT 4_P, CLK_SYNTH_DCLKOUT 4_N | Reference clock signal to FPGA MGT bank 115, pins T6/T5. |
| SDCLKout7, SDCLKout7* | CLK_SYNTH_SDCLKO UT7_P, CLK_SYNTH_SDCLKO UT7_N | Reference clock signal to FPGA MGT bank 118, pins F6/F5. |
| OSCout0, OSCout0* | CLK_SYNTH_CLKIN2_P, CLK_SYNTH_CLKIN2_N | Reference clock signal to FPGA bank 18, pins J30/J31 (100 nF decoupling capacitors). |

Table 17: Pin description of clock synthesizer TI LMK04828B.

Power and Power-On Sequence

Power Supply

6-pin 12V power connector J5 is the main power supply of the TEC0330 FPGA board, minimum current capability of 3A for system startup is recommended.

Power Consumption

| Power Input | Typical Current |
|-------------|-----------------|
| 12V (J5) | TBD |
| 3V3PCI (J1) | TBD |

Table 18: Typical power consumption.

TBD - To Be Determined.

Power-On Sequence

The on-board voltages of the TEC0330 FPGA board are powered up in predefined sequence after the external voltages 12V on connector J5 and 3V3PCI on connector J1 become available.

Core voltages and main supply voltages have to reach stable state and their "Power Good" signals have to be asserted before other voltages like PL bank's I/O voltages can be powered up.

Following diagram describes the sequence of enabling the on-board voltages:

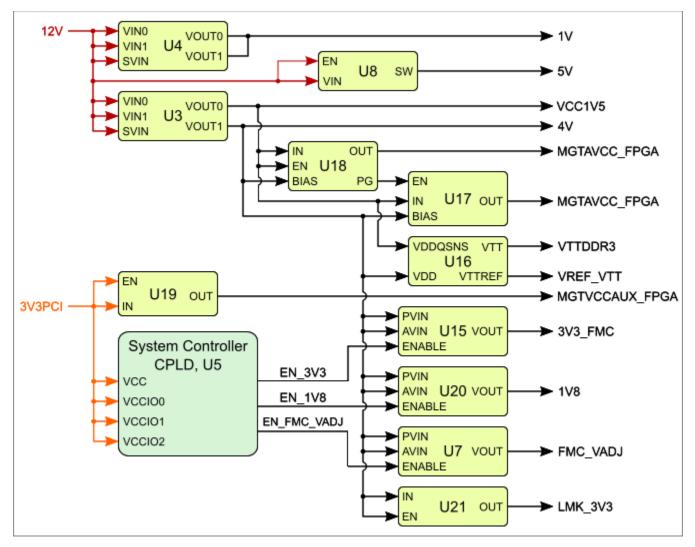


Figure 3: FPGA board TEC0330-03 power-on sequence diagram.

Bank Voltages

| Bank | Schematic Name | Voltage | Range | Notes |
|------|----------------|---------|------------------|---|
| 0 | 1V8 | 1.8V | HP: 1.2V to 1.8V | Config bank (fixed to 1.8V) / JTAG interface. |
| 14 | 1V8 | 1.8V | HP: 1.2V to 1.8V | QSPI flash memory interface. |
| 15 | 1V8 | 1.8V | HP: 1.2V to 1.8V | Reference clock input. |
| 16 | 1V8 | 1.8V | HP: 1.2V to 1.8V | I ² C interface of FPGA. |
| 17 | 1V8 | 1.8V | HP: 1.2V to 1.8V | Reference clock input. |
| 18 | 1V8 | 1.8V | HP: 1.2V to 1.8V | Reference clock input / I/O's to CPLD. |
| 34 | VCC1V5 | 1.5V | HP: 1.2V to 1.8V | DDR3 memory interface. |

| 35 | VCC1V5 | 1.5V | HP: 1.2V to 1.8V | DDR3 memory interface. |
|-----|----------------|------|---------------------------------------|--|
| 55 | 000103 | 1.50 | 111.1.20101.00 | DDR3 memory menace. |
| 36 | VCC1V5 | 1.5V | HP: 1.2V to 1.8V | DDR3 memory interface. |
| 114 | MGTAVCC_FPGA | 1.0V | MGT bank supply voltage | MGT banks with Xilinx GTH transceiver units. |
| 115 | MGTVCCAUX_FPGA | 1.8V | MGT bank auxiliary supply voltage | |
| 116 | MGTAVTT_FPGA | 1.2V | MGT bank termination circuits voltage | |
| 117 | | | | |
| 118 | | | | |
| 19 | 1V8 | 1.8V | HP: 1.2V to 1.8V | I/Os routed to FMC, usable as LVDS pairs. |
| 37 | 1V8 | 1.8V | HP: 1.2V to 1.8V | I/Os routed to FMC, usable as LVDS pairs. |
| 38 | 1V8 | 1.8V | HP: 1.2V to 1.8V | I/Os routed to FMC, usable as LVDS pairs. |
| 39 | VIO_B_FMC | user | HP: 1.2V to 1.8V | I/Os routed to FMC, usable as LVDS pairs. |

 Table 19: Range of FPGAs bank voltages.

See Xilinx Virtex-7 datasheet (DS183) for the voltage ranges allowed.

Power Rails

| Connector / Pin | Voltage | Direction | Notes |
|-------------------------------|----------------|-----------|---|
| J4, pin 2 | 12V (filtered) | Output | 4-wire PWM fan connector supply voltage |
| J6, pin 2 | 5V (filtered) | Output | Cooling fan M1 supply voltage |
| J8, pin 6 | 3V3PCI | Output | VCCIO CPLD JTAG |
| J9, pin 2 | 1V8 | Output | VCCIO FPGA JTAG |
| J2, pin C35 / C37 | 12V | Output | VCCIO FMC |
| J2, pin D32 | 3V3PCI | Output | VCCIO FMC |
| J2, pin D36 / D38 / D39 / D40 | 3V3FMC | Output | VCCIO FMC |
| J2, pin H1 | VREF_A_M2C | Input | VREF voltage for bank 37 / 38 |
| J2, pin K1 | VREF_B_M2C | Input | VREF voltage for bank 39 |
| J2, pin J39 / J40 | VIO_B_FMC | Input | PL I/O voltage bank 39 (VCCO) |
| J2, pin H40 / G39 / F40 / E39 | FMC_VADJ | Output | VCCIO FMC (fixed to 1.8V) |
| J1, pin A10 / A11 / B8 | 3V3PCI | Input | PCIe interface supply voltage |
| J5, pin 1 / 2 / 3 | 12V | Input | Main power supply connector |

Table 20: Power rails and corresponding connectors of the FPGA board.

Technical Specifications

Absolute Maximum Ratings

| Parameter | Min | Max | Units | Notes | Notes |
|-----------------------------|-------|---------------|-------|-----------|---|
| 12V power supply voltage | 11.4 | 12.6 | V | 12V ± 5 % | ANSI/VITA 57.1 FPGA Mezzanine Card (FMC) standard |
| PL I/O voltage for HP banks | -0.55 | VCCO_X + 0.55 | V | - | Xilinx datasheet DS183 |

| GTH transceivers | -0.5 | 1.26 | V | - | Xilinx datasheet DS183 |
|--|------|------|----|---|--------------------------|
| Voltage on System Controller CPLD pins | -0.3 | 3.6 | V | - | MachXO2 family datasheet |
| Storage temperature | -55 | +125 | °C | - | MachXO2 family datasheet |

Table 21: Absolute maximum ratings.

Recommended Operating Conditions

| Parameter | Min | Мах | Units | Notes | Reference Document |
|--|-------|--------------|-------|-----------|---|
| 12V power supply voltage | 11.4 | 12.6 | V | 12V ± 5 % | ANSI/VITA 57.1 FPGA Mezzanine Card (FMC) standard |
| PL I/O voltage for HP banks | -0.2 | VCCO_X + 0.2 | V | - | Xilinx datasheet DS183 |
| GTH transceivers | (*) | (*) | - | - | Xilinx datasheet DS183 |
| Voltage on System Controller CPLD pins | 3.135 | 3.6 | V | - | MachXO2 family datasheet |

Table 22: Recommended operation conditions.

A Check Xilinx datasheet (DS183) for complete list of absolute maximum and recommended operating ratings.

Operating Temperature Ranges

Commercial grade: 0°C to +70°C.

Industrial grade: -40°C to +85°C.

The FPGA board's operating temperature range depends also on customer design and cooling solution. Please contact us for options.

Physical Dimensions

- board size: 106,65mm × 167,65mm
- Mating height with standard FMC connectors: 10 mm
- PCB thickness: 1.65 mm

All dimensions are given in millimeters.

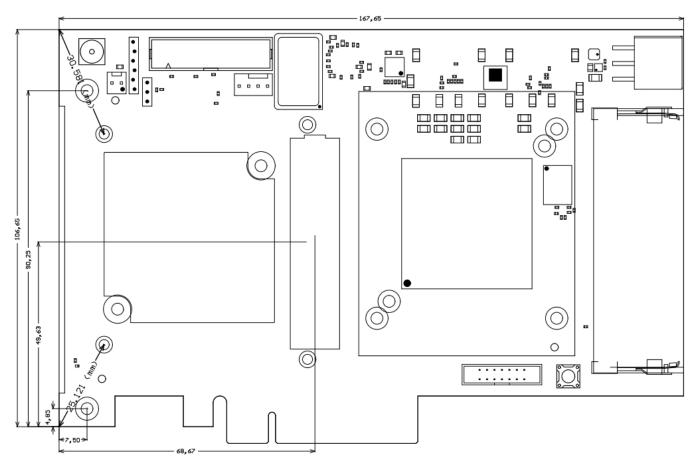


Figure 4: Physical dimensions of the TEC0330-03 board.

Hardware Revision History

| Date | Revision | Notes | PCN | Documentation |
|------------|----------|--------------------------|-----|---------------|
| - | 03 | First production release | - | - |
| 2015-11-05 | 02 | Prototype | - | - |
| - | 01 | Prototype | - | - |

Table 23: Hardware revision history.

Hardware revision number is printed on the PCB board together with the model number separated by the dash.



Figure 5: TE0330 board hardware revision number.

Document Change History

| Date | Revision | Contributors | Description |
|---|---------------------------|--------------|---|
| Error rendering macro 'page-info' Ambiguous method overloading for method jdk. proxy279.\$Proxy4022#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages. Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core. ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence. core.ContentEntityObject] | Unknown macro: 'metadata' | Jan Kumann | MGT Lanes section added. MGT banks clock sources table added. Fixed signal names in JTAG section. On- board periphera Is section added. Weight section removed. |
| 2017-08-30 | v.15 | Jan Kumann | Block diagram changed. Physical dimensio ns image changed. New product images. Correctio ns in content. Template revision added. |
| 2017-03-15 | v.3 | Ali Naseri | Initial TRM release. |

Table 24: Document change history.

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